Standardized Information for Process/Product Change Notification (PCN)

	1. PCN basic data TAIWAN SEMICONDUCTOR CO.,LTD		
1.1 Company TAIWAN SEMICONDUCTOR	TAIWAN SEMICONDUCTOR CO.,LTD		
1.2 PCN No.	PCN20008		
1.3 Title of PCN	Qualification of new subcon for SOD-123, SOD-323F, SOD-523F package		
1.4 Product Category	Active Components - Integrated Circuits		
1.5 Issue date	2020/08/14		
1.6 PCN revision history (optional)	1.7 Issue date of previous 1.8 Delta to previous revision (optional) revision (optional)		

2. PCN Team							
2.1 Contact supplier							
2.1.1 Name	Sunnie Lin						
2.1.2 Phone	+886-2-8913-1588 Ext:2205						
2.1.3 Email	sunnie.lin@mail.ts.com.tw						
2.2 Team supplier (optional)							
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)					
Chris Lin	+886 2 89131588 Ext.2406	chris_lin@mail.ts.com.tw					
Rolly Natividad	+886 2 89131588 Ext.2209	+886 2 89131588 Ext.2209 rolly.natividad@mail.ts.com.tw					

	3. Changes						
No.	3.0 Ident	3.1 Category	3.2 Type of change				
#1	SEM-DS-02	DATA SHEET	Correction of data sheet or issue of errata				
#2	SEM-PA-18	PROCESS - ASSEMBLY	Move all or parts of production to a different assembly site.				

	4. Description of change							
	Old	New						
Change #1	Datasheet Correction	Datasheet Correction						
	Ordering information remove factory code : 1. RB751V-40WS	Ordering information remove factory code : 1. RB751V-40WS						
	SOD-323F POD thickness (0.8~1.10 mm) change : 1. BAS316WS 2. BAT42WS 3. BAV19WS 4. RB751V-40WS	SOD-323F POD thickness change to (0.6~1.0mm): 1. BAS316WS 2. BAT42WS 3. BAV19WS 4. RB751V-40WS						
	Forward current derating curve : 1. BAT42WS/BAT43WS	Revise forward current derating curve (IF current:200mA) : 1. BAT42WS/BAT43WS						
	No test item (thermal performance) 1. BAS316WS	Add test item (thermal performance) 1. BAS316WS						
	No VZ@IZ curve follow test result 1. BZX584B series 2. BZT52Cxx-G series	Add VZ@IZ curve follow test result 1. BZX584B series 2. BZT52Cxx-G series						

Change #2	Current Subcon : Subcon A for :	Additional Subcon : Subcon E for :
	1. SOD-123 (SKY, SWCH & Zener)	1. SOD-123 (SKY, Zener, SWCH)
		2. SOD-323F (SKY, SWCH)
	Subcon B for:	3. SOD-523F (SKY, Zener)
	1. SOD-123 (SKY, SWCH & Zener)	
	Subcon C for:	
	1. SOD-323F (SKY & SWCH)	
	2. SOD-523F (SKY)	
	Subcon D for:	
	1. SOD-523F (Zener)	
	Note: Subcon A, B, C & D will continue mass production	
	support.	
4.1 Anticipated impact on		
form, fit, function, reliability		
or processability?	This shapes will have no impost on any of the electrics	I was a section of the area direct involve. The area direct took
	This change will have no impact on any of the electrical	hanged. Subcon "E" facility will produce products with the
	same level of quality and reliability as the existing man	
	In addition there will be no changes in POD (no impact	on form, fit and function).
4.2 Reference parts with		
customer number (optional)		

5. Reason / motivation for change					
5.1 Motivation	Subcon E is capable to support assembly of SOD-123, SOD-323F and SOD-523F packages with the level of quality and reliability comparable to the existing subcon sites. This products are assmbled in SOD-123, SOD-323F and SOD-523F packages. Subcon A, B, C, D currently assembles these products.				
5.2 Additional explanation (optional)	Taiwan Semiconductor Co., LTD (TSC) is qualifying Subcon "E" as an alternate assembly and test location for SOD-123, SOD-323F and SOD-523F package types. Subcon "E" is an ISO 9001 and IATF 16949 certified company. TSC will also continue to assemble and test SOD-123, SOD-323F and SOD-523F products using existing qualified suppliers. The additional flexibility resulting from the qualification of Subcon "E" will give TSC improved ability to respond to large orders with minimum lead times. All of the sites are currently qualified and utilized in high volume production by TSC for very similar products.				

6. Marking of parts / traceability of change			
6.1 Description	Use factory code for traceability		

7. Timing / schedule					
7.1 Date of qualification results	2020/06/18				
7.2 Last order date (optional)		N/A			
7.3 Last delivery date (optional)		N/A			
7.4 Intended start of delivery	2020/11/12				
7.5 Qualification samples available?	Can be submitted 2 weeks upon receipt of customer order.				
7.6 Customer feedback required until	2020/09/28				

8. Qualification / validation							
8.1 Description (e.g. qual. plan/report, AEC-Q)	Qualification/validation is in accordance with applicable JESD22 and TSC qualification plan requirements.						
8.2 Qualification report and qualification results	available (see attachement)	issue date	2020/06/18				

Input to customer for risk assessment pro	ocess
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Human Resource : No Risk Equipment : No Risk Technology-Wafer : No Risk Assembly & Test : No Risk Form/ Fit / Function : No Risk Reliability : No Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

Refer to the official e-mail announcement for the applicable documents.

Customer Part Name Supplier Package Part Additional Supplier Supplier Part Package Additional	11. Affected parts									
Customer Part Name Supplier Part No. Part No. Part No. (optional) Part No. Part No. Part No. (optional) Part Description (optional) Additional Part Name Part Name Supplier Part No. Part Name No. (optional) Additional Part Name Part Name Optional)						11.2 New (if applicable)				
	11.1.1 Customer Part No.	11.1.2 Supplier Part Name	Supplier Part No.	Package	Part Description	Additional Part Informatio	Supplier	Supplier Part No.	Package	Additional Part Information